



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



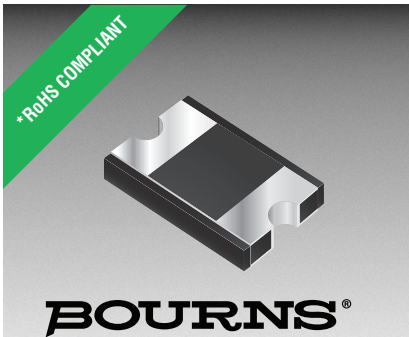
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## Features

- RoHS compliant\*
- Low profile
- Low power loss, high efficiency
- UL 94V-0 classification

## Applications

- Switch Mode Power Supplies
- Portable equipment batteries
- High frequency rectification
- DC/DC Converters
- Telecommunications

## CD214C-S3x Series Rectifier Chip Diode

### General Information

Portable communications, computing and video equipment manufacturers are challenging the semiconductor industry to develop increasingly smaller electronic components.

Bourns offers Glass Passivated Rectifiers for rectification applications in a compact chip package compatible with DO-214AB (SMC) size format. The Glass Passivated Rectifier Diodes offer a forward current of 3 A with a choice of repetitive peak reverse voltage of 200 V up to 1000 V.



### Absolute Maximum Ratings (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Parameter	Symbol	CD214C-					Unit
		S3D	S3G	S3J	S3K	S3M	
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	200	400	600	800	1000	V
Maximum Average Forward Current	I <sub>F(AV)</sub>	3					A
Maximum Peak Forward Surge Current (8.3 ms Single Half Sine-Wave)	I <sub>SM</sub>	100					A
Operating Junction Temperature Range	T <sub>OPR</sub>	-65 to +175					°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +175					°C

### Electrical Characteristics (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Maximum Instantaneous Forward Voltage (NOTE 1)	V <sub>F</sub>	I <sub>F</sub> = 3 A		0.96	1	V
DC Reverse Current	I <sub>R</sub>	V <sub>R</sub> = V <sub>RRM</sub>		0.1	5	μA
Typical Thermal Resistance (NOTE 2)	Junction to Ambient	R <sub>θJA</sub>		118		°C/W
	Junction to Lead	R <sub>θJL</sub>		32		

#### NOTES:

(1) Pulse width 300 microsecond, 1 % duty cycle.

(2) Mounted on PCB with 5.0 x 5.0 mm (0.2 x 0.2 inch) copper pad areas.

\*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

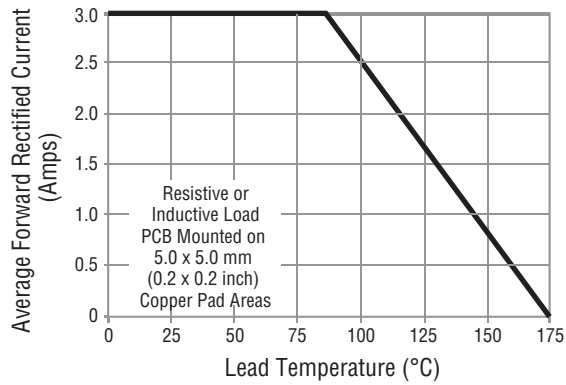
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

# CD214C-S3x Series Rectifier Chip Diode

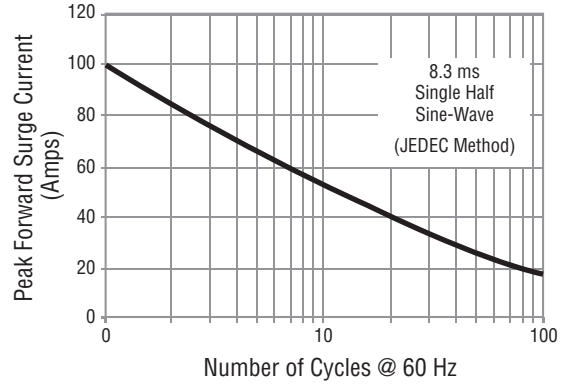
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## Performance Graphs

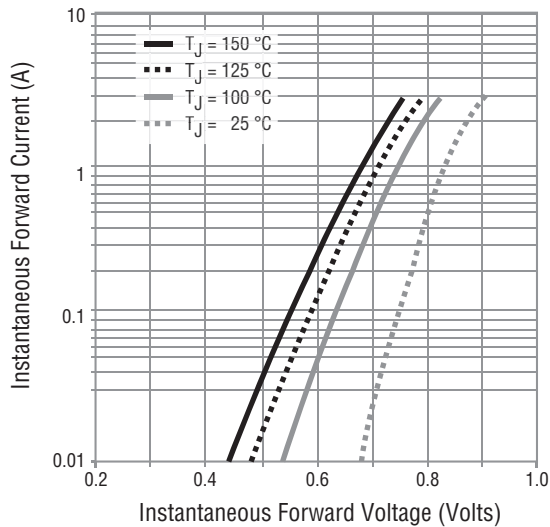
### Forward Current Derating Curve



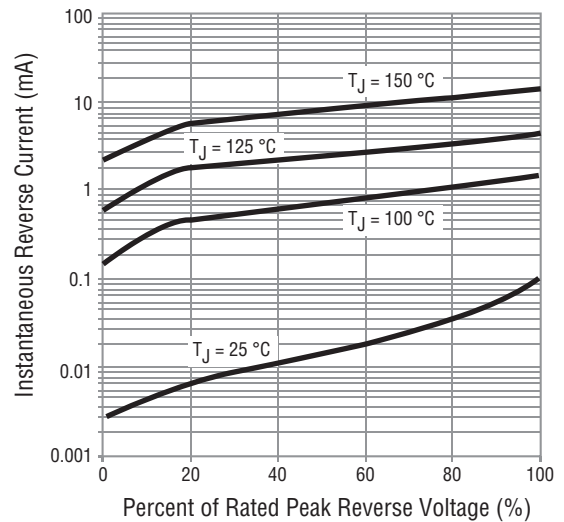
### Maximum Peak Forward Surge Current



### Typical Instantaneous Forward Characteristics



### Typical Reverse Characteristics

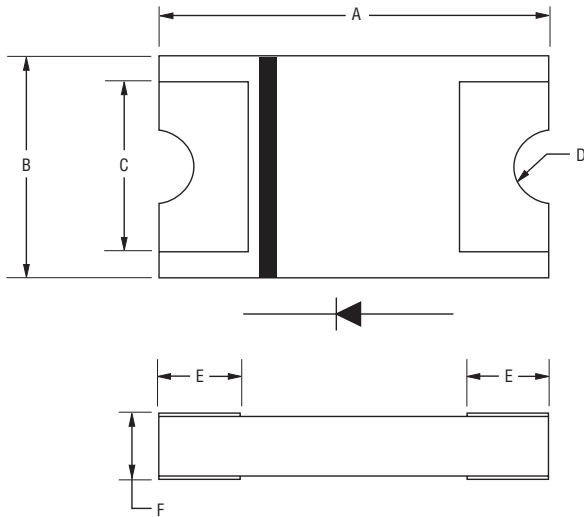


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# CD214C-S3x Series Rectifier Chip Diode



## Product Dimensions



Dimension	CD214C-S3 Series
A	$\frac{8.0 \pm 0.10}{(0.315 \pm 0.004)}$
B	$\frac{5.0 \pm 0.10}{(0.197 \pm 0.004)}$
C	$\frac{3.90}{(0.154)}$ TYP.
D	$\frac{0.80 \pm 0.02}{(0.031 \pm 0.001)}$
E	$\frac{1.95 \pm 0.10}{(0.077 \pm 0.004)}$
F	$\frac{1.10 \pm 0.15}{(0.043 \pm 0.006)}$

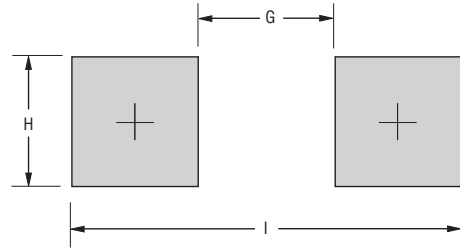
DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

## How to Order

**CD 214C - S 3 D**

- Common Code \_\_\_\_\_
- CD = Chip Diode
- Package \_\_\_\_\_
- 214C = SMC/DO-214AB Compatible
- Model \_\_\_\_\_
- S = Glass Passivated Rectifier Series
- Maximum Average Forward Rectified Current \_\_\_\_\_
- 3 = 3 A
- Maximum Repetitive Peak Reverse Voltage \_\_\_\_\_
- D = 200 V
- G = 400 V
- J = 600 V
- K = 800 V
- M = 1000 V

## Recommended Pad Layout



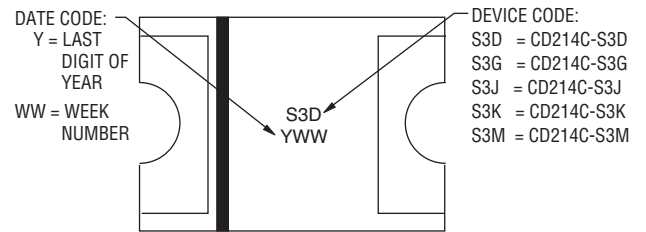
Dimension	CD214C-S3 Series
G	$\frac{4.10}{(0.161)}$ MAX.
H	$\frac{3.90}{(0.154)}$ MIN.
I	$\frac{11.90}{(0.469)}$ REF.

DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

## Environmental Specifications

Moisture Sensitivity Level..... 1  
 ESD Classification (HBM)..... 3B

## Typical Part Marking



DATE CODE:  
 Y = LAST  
 DIGIT OF  
 YEAR  
 WW = WEEK  
 NUMBER

DEVICE CODE:  
 S3D = CD214C-S3D  
 S3G = CD214C-S3G  
 S3J = CD214C-S3J  
 S3K = CD214C-S3K  
 S3M = CD214C-S3M

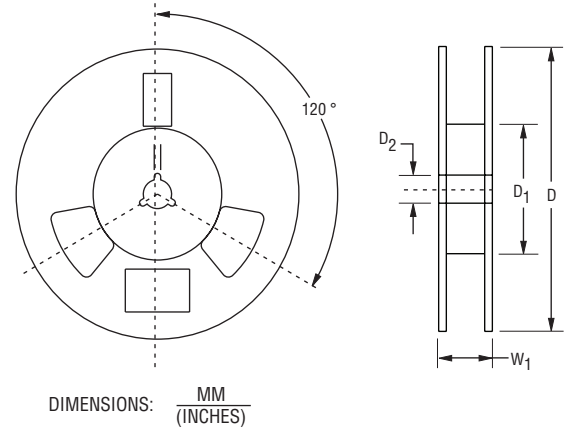
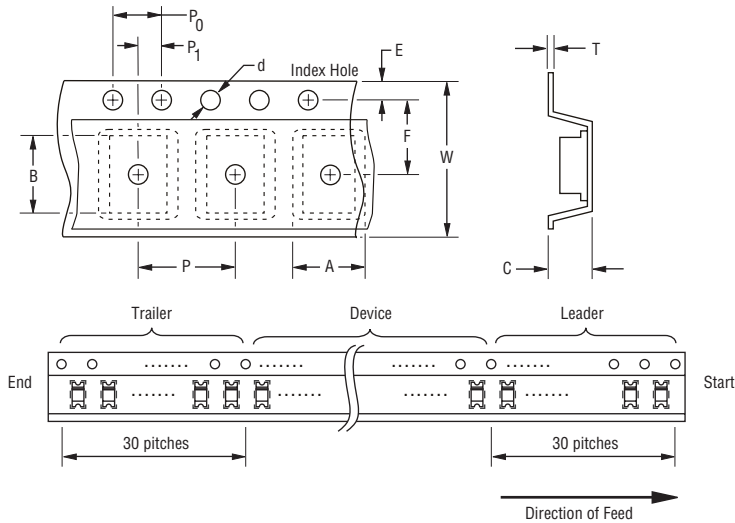
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# CD214C-S3x Series Rectifier Chip Diode

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## Packaging Information

The product is dispensed in tape and reel format (see diagram below).



Item	Symbol	CD214C-S3 Series
Carrier Width	A	$\frac{5.56 \pm 0.10}{(0.219 \pm 0.004)}$
Carrier Length	B	$\frac{8.18 \pm 0.10}{(0.322 \pm 0.004)}$
Carrier Depth	C	$\frac{2.50}{(0.098)}$ MAX.
Sprocket Hole	d	$\frac{1.55 \pm 0.05}{(0.061 \pm 0.002)}$
Reel Outside Diameter	D	$\frac{330 \pm 2.0}{(12.992 \pm 0.079)}$
Reel Inner Diameter	D <sub>1</sub>	$\frac{50.0}{(1.969)}$ MIN.
Feed Hole Diameter	D <sub>2</sub>	$\frac{13.0 \pm 0.50}{(0.512 \pm 0.020)}$
Sprocket Hole Position	E	$\frac{1.75 \pm 0.10}{(0.069 \pm 0.004)}$
Punch Hole Position	F	$\frac{7.50 \pm 0.10}{(0.295 \pm 0.004)}$
Punch Hole Pitch	P	$\frac{8.00 \pm 0.10}{(0.315 \pm 0.004)}$
Sprocket Hole Pitch	P <sub>0</sub>	$\frac{4.00 \pm 0.10}{(0.157 \pm 0.004)}$
Embossment Center	P <sub>1</sub>	$\frac{2.00 \pm 0.10}{(0.079 \pm 0.004)}$
Overall Tape Thickness	T	$\frac{0.40}{(0.016)}$ MAX.
Tape Width	W	$\frac{16.00 \pm 0.30}{(0.630 \pm 0.012)}$
Reel Width	W <sub>1</sub>	$\frac{22.7}{(0.893)}$ MAX.
Quantity per Reel	--	3,000

**BOURNS®**

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